

ULTRAFAST SOFT RECOVERY RECTIFIER DIODE

PRODUCT APPLICATIONS

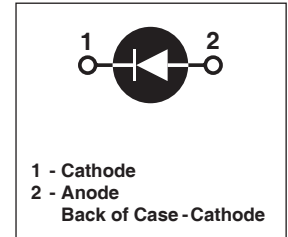
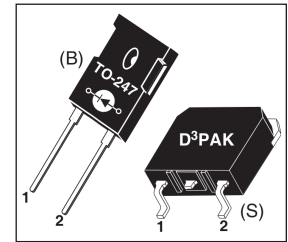
- Anti-Parallel Diode
 - Switchmode Power Supply
 - Inverters
- Free Wheeling Diode
 - Motor Controllers
 - Converters
 - Inverters
- Snubber Diode
- PFC

PRODUCT FEATURES

- Ultrafast Recovery Times
- Soft Recovery Characteristics
- Popular TO-247 Package or Surface Mount D³PAK Package
- Low Forward Voltage
- Low Leakage Current

PRODUCT BENEFITS

- Low Losses
- Low Noise Switching
- Cooler Operation
- Higher Reliability Systems
- Increased System Power Density



MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT60D100(B/S)G	UNIT
V_R	Maximum D.C. Reverse Voltage	1000	Volts
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		
V_{RWM}	Maximum Working Peak Reverse Voltage		
$I_{F(AV)}$	Maximum Average Forward Current ($T_C = 142^\circ\text{C}$, Duty Cycle = 0.5)	60	Amps
$I_{F(AV)}$	RMS Forward Current (Square wave, 50% duty)	152	
I_{FSM}	Non-Repetitive Forward Surge Current ($T_J = 45^\circ\text{C}$, 8.3ms)	540	
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 175	$^\circ\text{C}$
T_L	Lead Temperature for 10 Sec.	300	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
V_F	Forward Voltage		$I_F = 60\text{A}$	1.9	Volts
			$I_F = 120\text{A}$	2.2	
			$I_F = 60\text{A}, T_J = 125^\circ\text{C}$	1.7	
I_{RM}	Maximum Reverse Leakage Current		$V_R = V_R$ Rated	250	μA
			$V_R = V_R$ Rated, $T_J = 125^\circ\text{C}$	500	
C_T	Junction Capacitance, $V_R = 200\text{V}$		65		pF

DYNAMIC CHARACTERISTICS

APT60D100(B/S)G

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
t_{rr}	Reverse Recovery Time	$I_F = 1A$, $di_F/dt = -100A/\mu s$, $V_R = 30V$, $T_J = 25^\circ C$	-	34		ns
t_{rr}	Reverse Recovery Time	$I_F = 60A$, $di_F/dt = -200A/\mu s$ $V_R = 667V$, $T_C = 25^\circ C$	-	280		
Q_{rr}	Reverse Recovery Charge		-	760		nC
I_{RRM}	Maximum Reverse Recovery Current		-	6	-	Amps
t_{rr}	Reverse Recovery Time	$I_F = 60A$, $di_F/dt = -200A/\mu s$ $V_R = 667V$, $T_C = 125^\circ C$	-	350		ns
Q_{rr}	Reverse Recovery Charge		-	3600		nC
I_{RRM}	Maximum Reverse Recovery Current		-	16	-	Amps
t_{rr}	Reverse Recovery Time	$I_F = 60A$, $di_F/dt = -1000A/\mu s$ $V_R = 667V$, $T_C = 125^\circ C$	-	170		ns
Q_{rr}	Reverse Recovery Charge		-	5650		nC
I_{RRM}	Maximum Reverse Recovery Current		-	50		Amps

THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-Case Thermal Resistance			.21	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance			40	
W_T	Package Weight		0.22		oz
			5.9		g
Torque	Maximum Mounting Torque			10	lb•in
				1.1	N•m

APT Reserves the right to change, without notice, the specifications and information contained herein.

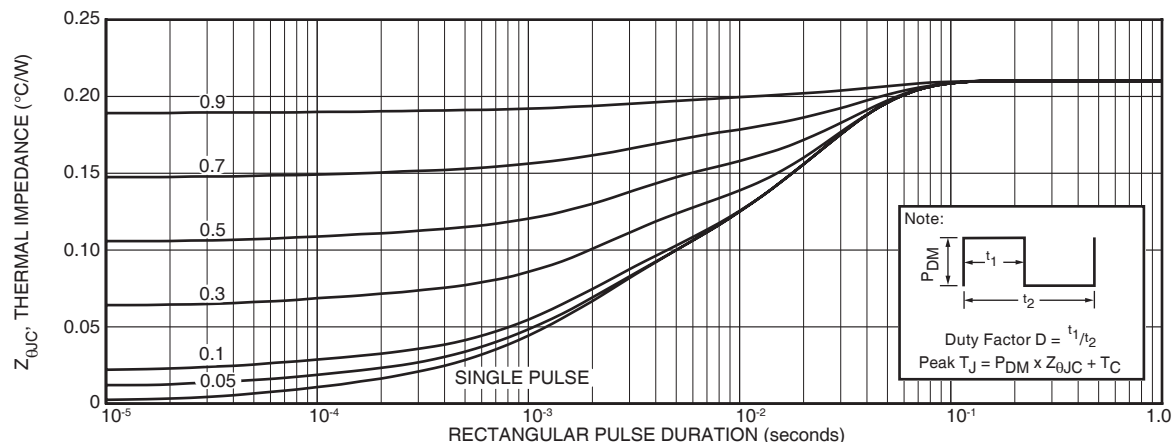


FIGURE 1a. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

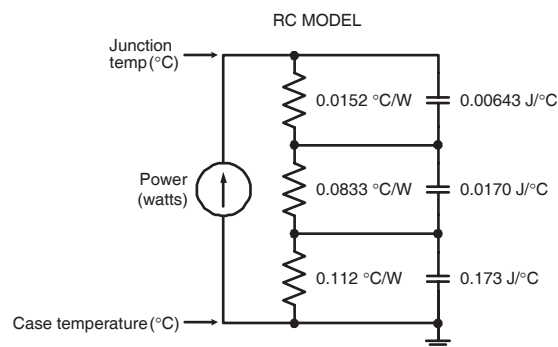


FIGURE 1b. TRANSIENT THERMAL IMPEDANCE MODEL

TYPICAL PERFORMANCE CURVES

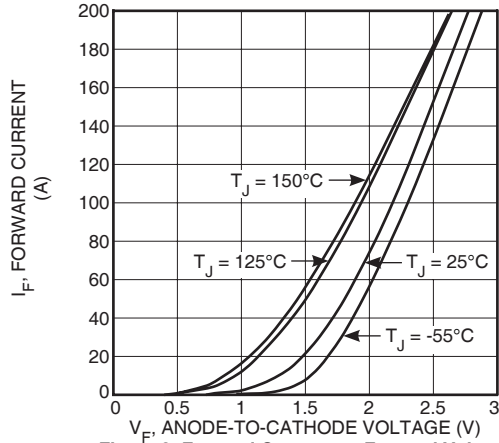


Figure 2. Forward Current vs. Forward Voltage

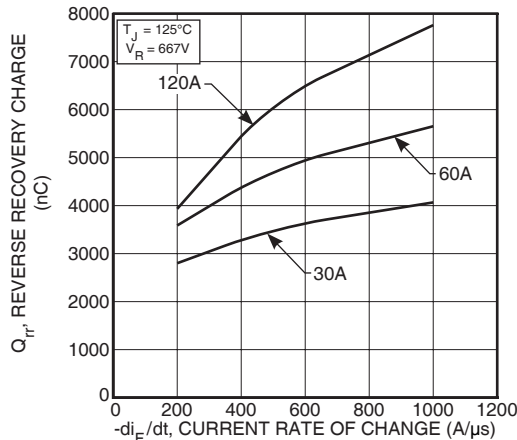


Figure 4. Reverse Recovery Charge vs. Current Rate of Change

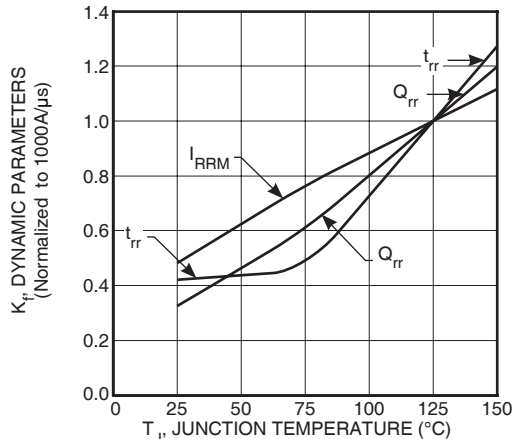


Figure 6. Dynamic Parameters vs. Junction Temperature

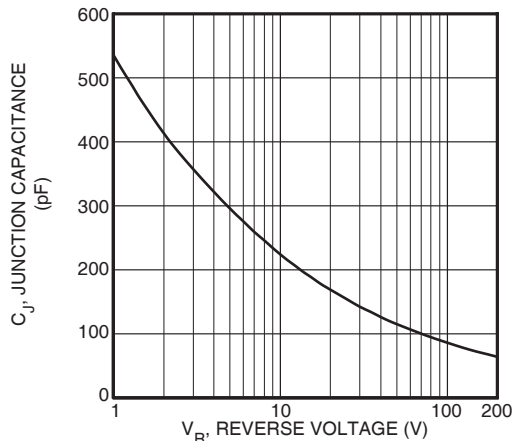


Figure 8. Junction Capacitance vs. Reverse Voltage

APT60D100(B/S)G

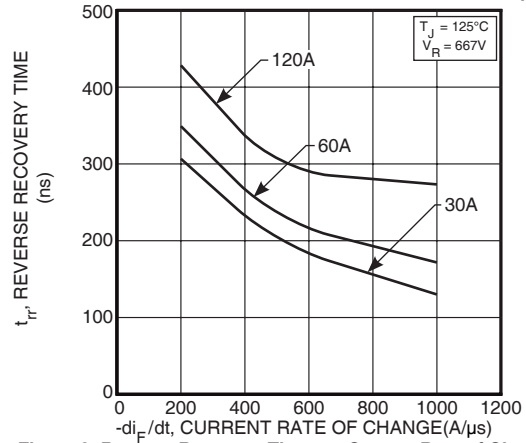


Figure 3. Reverse Recovery Time vs. Current Rate of Change

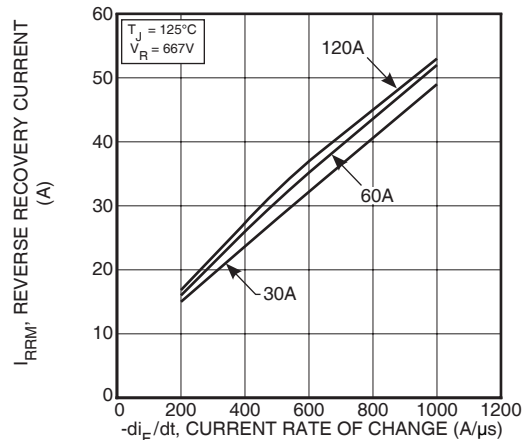


Figure 5. Reverse Recovery Current vs. Current Rate of Change

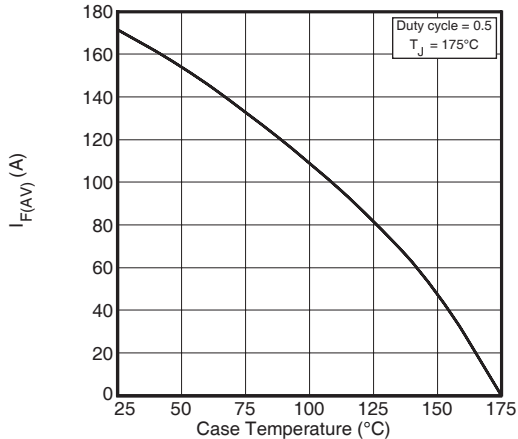


Figure 7. Maximum Average Forward Current vs. Case Temperature



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Figure 10, Diode Reverse Recovery Waveform and Definitions

D³PAK Package Outline

[illegible]

Figure 1: Dimensions of the Cathode and Leads

Dimensions in Millimeters (Inches)

Cathode (Heat Sink)

4.90 (.193)
5.10 (.201)
1.45 (.057)
1.60 (.063)

0.40 (.016)
0.65 (.026)
0.020 (.001)
0.250 (.010)
2.70 (.106)
2.90 (.114)

Top View

15.85 (.624)
16.05 (.632)

1.00 (.039)
1.15 (.045)

18.70 (.736)
19.10 (.752)

1.20 (.047)
1.40 (.055)

1.90 (.075)
2.10 (.083)

5.45 (.215) BSC (2 Plcs.)

Bottom View

13.30 (.524)
13.60 (.535)

12.40 (.488)
12.70 (.500)

2.40 (.094)
2.70 (.106) (Base of Lead)

Heat Sink (Cathode) and Leads are Plated

Anode Cathode



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